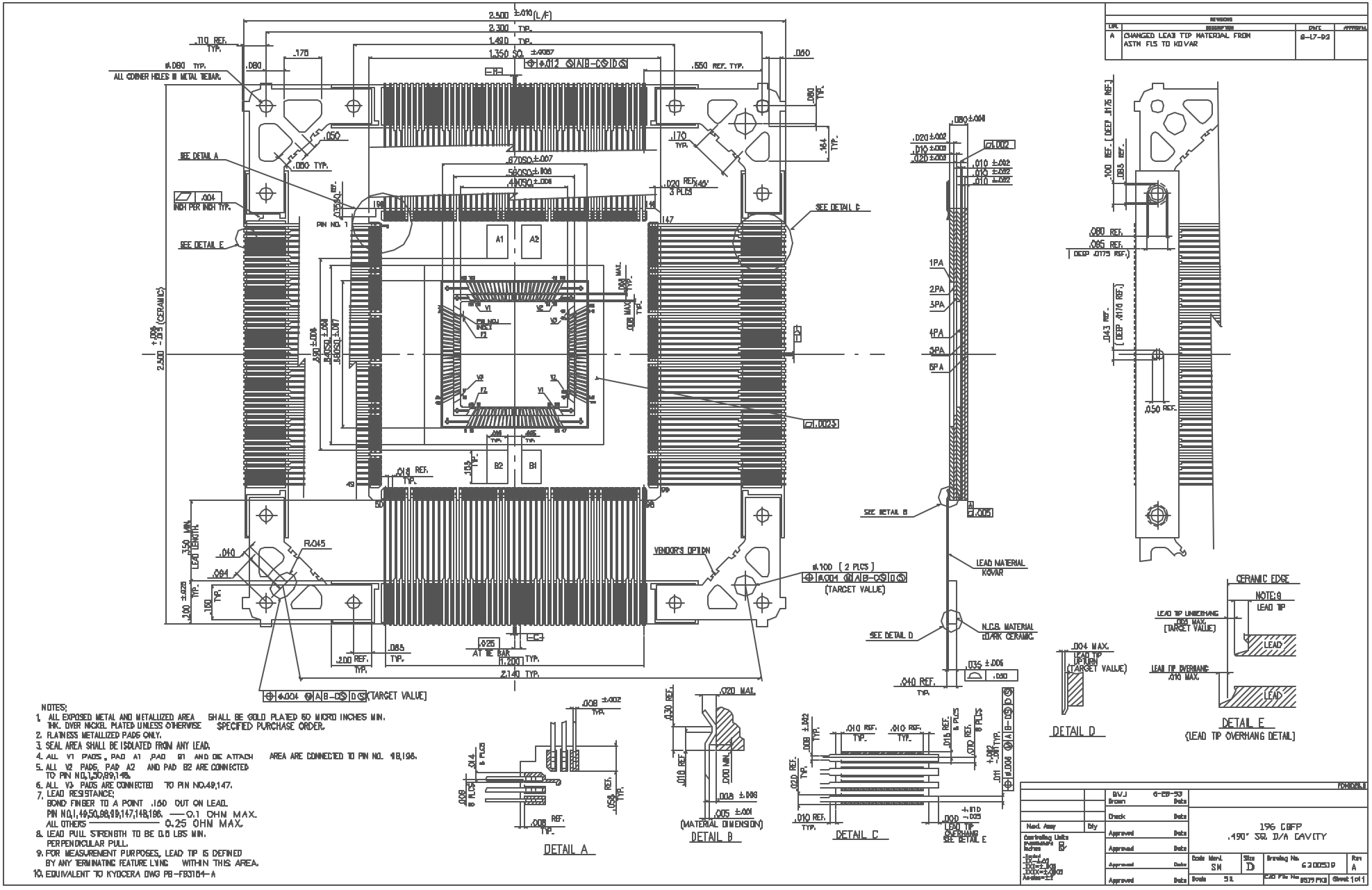
SSM P/N CCF19611



REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	CHANGED LEAD TIP MATERIAL FROM ASTM F15 TO KOVAR	8-17-93	

NOTES:
1. ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCHES MIN. THK. OVER NICKEL PLATED UNLESS OTHERWISE SPECIFIED PURCHASE ORDER.
2. FLATNESS METALLIZED PADS ONLY.
3. SEAL AREA SHALL BE ISOLATED FROM ANY LEAD.
4. ALL V1 PADS, PAD A1, PAD B1 AND DIE ATTACH AREA ARE CONNECTED TO PIN NO. 98,196.
5. ALL V2 PADS, PAD A2 AND PAD B2 ARE CONNECTED TO PIN NO.1,50,99,148.
6. ALL V3 PADS ARE CONNECTED TO PIN NO.49,147.
7. LEAD RESISTANCE; BOND FINGER TO A POINT .160 OUT ON LEAD. PIN NO.1,49,50,98,99,147,148,196. —0.1 OHM MAX. ALL OTHERS —— 0.25 OHM MAX.
8. LEAD PULL STRENGTH TO BE 0.6 LBS MIN. PERPENDICULAR PULL.
9. FOR MEASUREMENT PURPOSES, LEAD TIP IS DEFINED BY ANY TERMINATING FEATURE LYING WITHIN THIS AREA.
10. EQUIVALENT TO KYOCERA DWG PB-F83184-A

BVJ Brown	6-28-93 Date		
Check	Date		
Approved	Date	196 CBFP .490" SQ. D/A CAVITY	
Approved	Date		
Approved	Date	Scale Mem. SM / Size D / Drawing No. 63000519 / Rev A	
Approved	Date	Scale SM / CAD File No. 8629.PKG / Sheet 1 of 1	

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408.435.5555 Fax: 408.435.8226